



In re: Application of: Shooshtarian, et al. )  
Serial No.: 09/527,873 )  
Filed: March 17, 2000 )  
Confirmation No.: 4182 )  
Title: LOCALIZED HEATING AND COOLING OF )  
SUBSTRATES )

Group Art Unit: 2823  
Examiner: Hsein-Ming Lee  
Our Account No.: 04-1403

Commissioner for Patents  
U.S. Patent and Trademark Office  
Washington, DC 20231

**AMENDMENT**

This is a AMENDMENT in the above-identified application and includes the herewith attachment of same date and subject which is incorporated hereinto by reference and the signature below is to be treated as the signature to the attachment in absence of a signature thereto.

Fee requirements (if any) have been calculated as shown below:

	Claims remaining after amendment	Highest number previously paid for	Present Extra		Additional Fee
Total Effective Claims	_____	minus _____	= _____	x \$18 =	\$ _____
Independent Claims	_____	minus _____	= _____	x \$80 =	\$ _____
If amendment enters <u>proper</u> multiple dependent claim(s) into this application for <u>first</u> time, add \$270.00 (per application)					\$ _____
Since Official Action set an <u>original</u> due date of _____, <b>PETITION</b> is hereby made for an extension to cover the date this response is filed for which the requisite fee is enclosed (1 month \$110; 2 months \$390; 3 months \$890; 4 months \$1390)					\$ _____
If Terminal Disclaimer enclosed, add Rule 20(d) Official Fee (\$110.00)					\$ _____
<b>SUBTOTAL:</b>					\$ _____
If "small entity" verified statement filed [ ] previously, [ ] herewith, enter one-half (1/2) of subtotal and <u>subtract</u>					\$ _____
<b>TOTAL:</b>					\$ _____
Other: <u>Information Disclosure Statement List with References &amp; Information</u>					\$180.00
<u>Disclosure Statement Cover Sheet; and fee; Letter of Disclosure</u>					
<b>TOTAL FEE ENCLOSED:</b>					\$180.00

The Commissioner is hereby authorized to charge any fee specifically authorized hereafter, or any fees in addition to the fee(s) filed, or asserted to be filed, or which should have been filed herewith or concerning any paper filed hereafter, and which may be required under Rules 16-18 (deficiency only) now or hereafter relative to this application and the resulting official document under Rule 20, or credit any overpayment, to our Account No. shown in the heading hereof for which purpose a duplicate copy of this sheet is attached. This statement does not authorize charge of the issue fee in this case.

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**DORITY & MANNING**  
**ATTORNEYS AT LAW, P.A.**  
By Atty: Jason W. Johnston Reg. No.: 45,675  
Signature:

I hereby certify that this correspondence and any referenced attachment and fee are being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, U.S. Patent and Trademark Office, Washington, DC 20231, on April 18, 2001.

Lynn D. Hofer  
(Typed or printed name of person mailing paper or fee)  
  
(Signature of person mailing paper or fee)



**PATENT**  
**ATTORNEY DOCKET NO.: AGX-37**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application	)	
Shooshtarian, et al.	)	Examiner: Hsein-Ming Lee
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Serial No.: 09/527,873	)	Art Unit: 2823
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Filed: March 17, 2000	)	Dept. Acct. No.: 04-1403
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Title: Localized Heating and	)	
Cooling of Substrates	)	

11/B  
FJONES  
5-1-01

Commissioner for Patents  
Washington, D.C. 20231

**AMENDMENT**

Dear Sir:

In response to the Office Action dated February 14, 2001, please amend the above-captioned application as follows:

**IN THE CLAIMS:**

Please cancel claim 3.

Please amend claims 1, 4-5, 11, and 13 to read as follows (See also Appendix

A):

1. (Amended) A method for heat treating a semiconductor wafer, said method comprising the steps of  
placing a semiconductor wafer in a thermal processing chamber, said semiconductor wafer defining a plurality of localized regions along a radial axis;

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